International TOR Rectifier

POWER MOSFET THRU-HOLE (TO-254AA)

IRFM360 400V, N-CHANNEL HEXFET® MOSFET TECHNOLOGY

Product Summary

Part Number	RDS(on)	ΙD	
IRFM360	0.20 Ω	23A	

HEXFET® MOSFET technology is the key to International Rectifier's advanced line of power MOSFET transistors. The efficient geometry design achieves very low on-state resistance combined with high transconductance. HEXFET transistors also feature all of the well-established advantages of MOSFETs, such as voltage control, very fast switching, ease of paralleling and electrical parameter temperature stability. They are well-suited for applications such as switching power supplies, motor controls, inverters, choppers, audio amplifiers, high energy pulse circuits, and virtually any application where high reliability is required. The HEXFET transistor's totally isolated package eliminates the need for additional isolating material between the device and the heatsink. This improves thermal efficiency and reduces drain capacitance.



Features:

- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed
- Electrically Isolated
- Dynamic dv/dt Rating
- Light-weight

Absolute Maximum Ratings

	Parameter		Units	
ID @ VGS = 10V, TC = 25°C	Continuous Drain Current	23		
ID @ VGS = 10V, TC = 100°C	Continuous Drain Current	14	Α	
IDM	Pulsed Drain Current ①	92	1	
PD @ T _C = 25°C	Max. Power Dissipation	250	W	
	Linear Derating Factor	2.0	W/°C	
VGS	Gate-to-Source Voltage	±20	V	
EAS	Single Pulse Avalanche Energy ②	980	mJ	
IAR	Avalanche Current ①	23	Α	
EAR	Repetitive Avalanche Energy ①	25	mJ	
dv/dt	Peak Diode Recovery dv/dt 3	4.0	V/ns	
TJ	Operating Junction	-55 to 150		
TSTG	Storage Temperature Range		°C	
	Lead Temperature	300 (0.063 in.(1.6mm) from case for 10s)		
	Weight	9.3 (Typical)	g	

For footnotes refer to the last page

Electrical Characteristics @ Tj = 25°C (Unless Otherwise Specified)

	Parameter	Min	Тур	Max	Units	Test Conditions
BVDSS	Drain-to-Source Breakdown Voltage	400	_	_	V	$V_{GS} = 0V$, $I_{D} = 1.0$ mA
ΔBV _{DSS} /ΔT _J	Temperature Coefficient of Breakdown Voltage	_	0.46	_	V/°C	Reference to 25°C, I _D = 1.0mA
RDS(on)	Static Drain-to-Source On-State	_	_	0.20	Ω	VGS = 10V, ID = 14A
	Resistance	_	_	0.23	32	VGS = 10V, ID = 23A
VGS(th)	Gate Threshold Voltage	2.0	_	4.0	V	V _{DS} = V _{GS} , I _D = 250μA
9fs	Forward Transconductance	1.4	_	_		V _{DS} = 15V, I _{DS} = 14A ④
IDSS	Zero Gate Voltage Drain Current	_	_	25	μΑ	V _{DS} = 320V ,V _{GS} =0V
		_	_	250	μΑ	V _{DS} = 320V,
						$V_{GS} = 0V, T_{J} = 125^{\circ}C$
IGSS	Gate-to-Source Leakage Forward	_	_	100	^	VGS = 20V
IGSS	Gate-to-Source Leakage Reverse	_	_	-100	nA	Vgs = -20V
Qg	Total Gate Charge		_	210		VGS =10V, ID = 23A
Qgs	Gate-to-Source Charge	_	_	28	nC	$V_{DS} = 200V$
Q _{gd}	Gate-to-Drain ('Miller') Charge	_	_	120		
^t d(on)	Turn-On Delay Time		_	33		$V_{DD} = 200V, I_D = 23A,$
tr	Rise Time	_	_	140		$V_{GS} = 10V$, $R_{G} = 2.35\Omega$
^t d(off)	Turn-Off Delay Time	_	_	120	ns	
tf	Fall Time	_	_	99		
LS+LD	Total Inductance	_	6.8	_	nH	Measured from drain lead (6mm/ 0.25in. from package) to source lead (6mm/0.25in. from package)
C _{iss}	Input Capacitance	_	4200	_		$V_{GS} = 0V, V_{DS} = 25V$
Coss	Output Capacitance	_	900	_	pF	f = 1.0MHz
C _{rss}	Reverse Transfer Capacitance	_	400	_		

Source-Drain Diode Ratings and Characteristics

	Parameter		Min	Тур	Max	Units	Test Conditions
Is	Continuous Source Current	(Body Diode)	_	_	23	_	
ISM	Pulse Source Current (Body	Diode) ①	_	_	92	Α	
VSD	Diode Forward Voltage		_	_	1.8	V	$T_j = 25$ °C, $I_S = 23A$, $V_{GS} = 0V$ ④
t _{rr}	Reverse Recovery Time		_	_	1000	nS	Tj = 25°C, IF = 23A, di/dt ≤ 100A/μs
QRR	Reverse Recovery Charge		_	_	16	μC	V _{DD} ≤ 50V ④
ton	Forward Turn-On Time Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by L _S + L _D .						

Thermal Resistance

	Parameter	Min	Тур	Max	Units	Test Conditions
RthJC	Junction-to-Case	_	_	0.5		
RthCS	Csae-to-sink	_	0.21	_	°C/W	
R _{th} JA	Junction-to-Ambient	_	_	48		Typical socket mount

Note: Corresponding Spice and Saber models are available on International Rectifier Website.

For footnotes refer to the last page

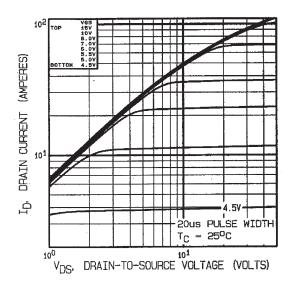


Fig 1. Typical Output Characteristics

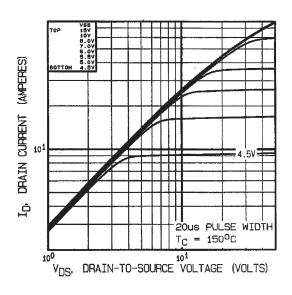


Fig 2. Typical Output Characteristics

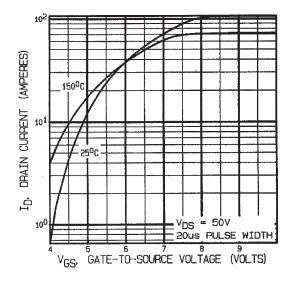


Fig 3. Typical Transfer Characteristics

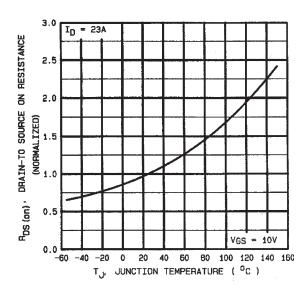


Fig 4. Normalized On-Resistance Vs. Temperature

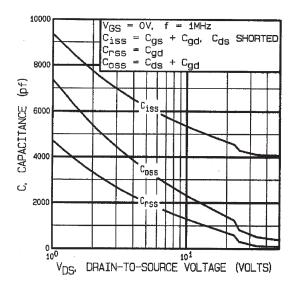


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

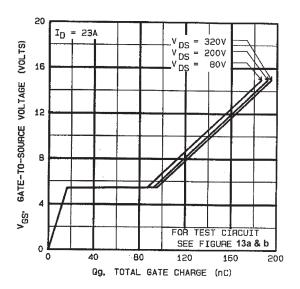


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

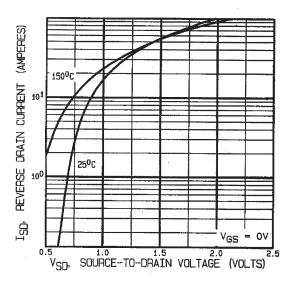


Fig 7. Typical Source-Drain Diode Forward Voltage

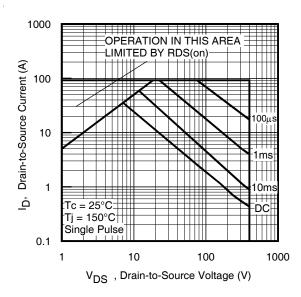


Fig 8. Maximum Safe Operating Area

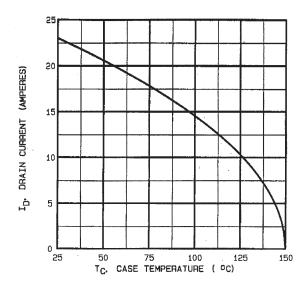


Fig 9. Maximum Drain Current Vs. Case Temperature

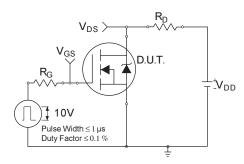


Fig 10a. Switching Time Test Circuit

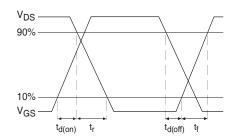


Fig 10b. Switching Time Waveforms

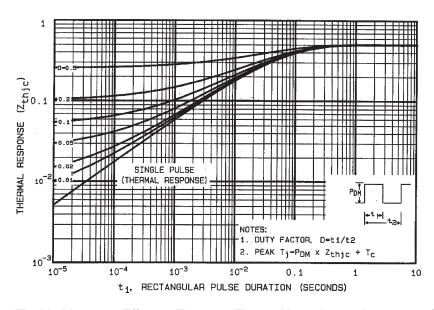


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

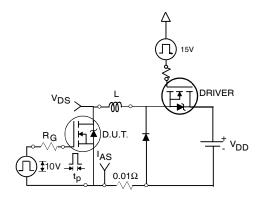


Fig 12a. Unclamped Inductive Test Circuit

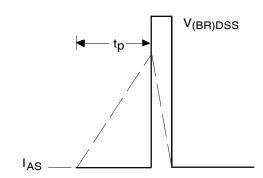


Fig 12b. Unclamped Inductive Waveforms

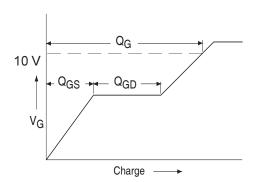


Fig 13a. Basic Gate Charge Waveform

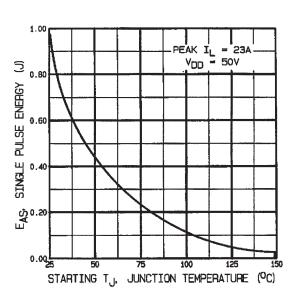


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

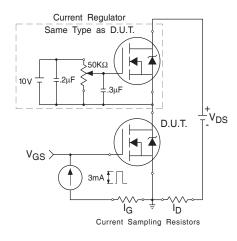


Fig 13b. Gate Charge Test Circuit

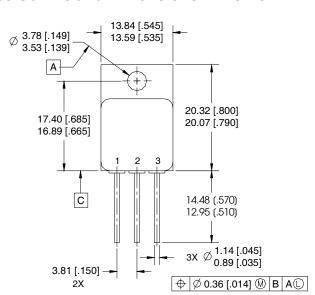
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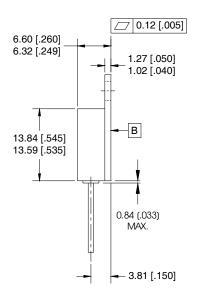
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Footnotes:

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
- $^{\circ}$ V_{DD} = 50V, starting T_J = 25°C, L= 3.7mH Peak I_L = 23A, V_{GS} = 10V
- $\label{eq:interpolation} \begin{array}{ll} \text{(3)} & I_{SD} \leq 23A, \ di/dt \leq 170A/\mu s, \\ & V_{DD} \leq 400V, \ T_{J} \leq 150^{\circ}C \end{array}$
- 4 Pulse width \leq 300 μ s; Duty Cycle \leq 2%

Case Outline and Dimensions — TO-254AA





NOTES:

- 1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
- 2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
- CONTROLLING DIMENSION: INCH.
- 4. CONFORMS TO JEDEC OUTLINE TO-254AA.

PIN ASSIGNMENTS

- 1 = DRAIN
- 2 = SOURCE
- 3 = GATE

CAUTION

BERYLLIA WARNING PER MIL-PRF-19500

Package containing beryllia shall not be ground, sandblasted, machined, or have other operations performed on them which will produce beryllia or beryllium dust. Furthermore, beryllium oxide packages shall not be placed in acids that will produce fumes containing beryllium.



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